

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
Name	Execution Date
Tzung-Chi LEE	08/10/2009
<b>RECEIVING PARTY DATA</b>	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
<b>PROPERTY NUMBERS Total: 1</b>	
Property Type	Number
Application Number:	12471091
<b>CORRESPONDENCE DATA</b>	
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ATTORNEY DOCKET NUMBER:	24061.1038
NAME OF SUBMITTER:	Liem T. Do
Total Attachments: 1 source=24061_1038_Assignment#page1.tif	

CH \$40.00 12471091

**ASSIGNMENT**

WHEREAS, I, Tzung-Chi LEE, of Banciao City, Taipei County 2009, Taiwan, R.O.C., has invented certain improvements in

**DEVICE LAYOUT FOR GATE LAST PROCESS**

for which I filed a patent application for letters patent in the United States of America on May 22, 2009, as U.S. Patent Application Serial No. 12/471,091.

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., (hereinafter "ASSIGNEE", of No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and I hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

First Inventor Name: Tzung-Chi LEE

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Dated: August 10, 2009

Tzung-Chi Lee  
Inventor Signature

Dated: August 10, 2009

Chou  
Witness Signature  
Witness Name: Chou